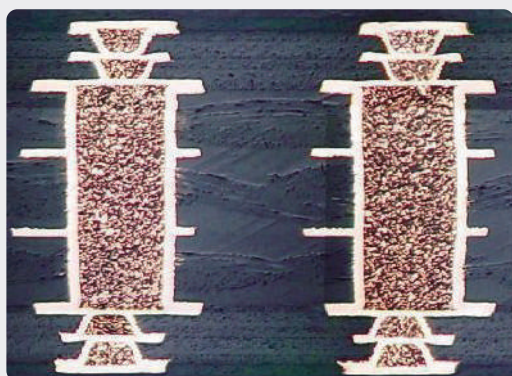


Conductive Via Filling Paste

Widely applicable from consumer electronics to industrial equipment

Applications

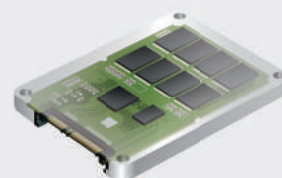
Heat release/inter-layer connection



Cross-section

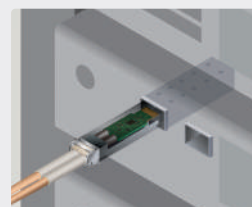
Consumer electronics

e.g. : SSD



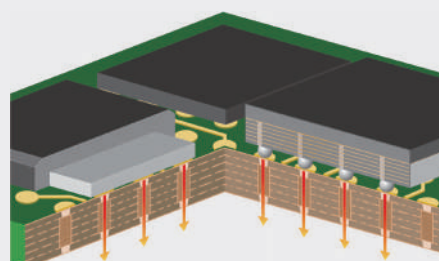
Telecommunication equipment

e.g. : Photonics transceiver



Features

- Excellent adhesion to various material surfaces including copper foil
- Stable electrical conductivity
- High heat release (AE7332: 38W/m·k)
- Solvent-free enabling void/crack-free
- Contribution to high-density routing and/or multi-layer build-up
- Wide range line-up for your needs



Thermal release

Product line-up & properties

Product			AE1244	AE2217	AE1650	AE3030	AE7332
Filler	Conductive particles		Silver coated copper				
	Average particle size	μm	5 - 6		2 - 3	5 - 6	3 - 8
Binder	Resin		Epoxy				
Viscosity	BH type	dPa·s	800 - 1,400	1,600 - 2,200	1,300 - 1,800	1,200 - 1,800	900 - 1,500
Density		g/cm ³	4.4 - 4.8		4.6 - 5.0	4.0 - 4.4	5.1 - 5.5
Curing conditions	Pre-curing		80℃×30min.	60℃×30min.	80℃×30min.	60℃×30min.	80℃×30min.
	Post-curing		160℃×60min.				
Volume resistivity(Representative value)		Ω·cm	1.0E-04			2.0E-04	5.0E-05
Thermal conductivity (Laser flash method)		W/m·k	11.7	13.5	16.5	7.8	38
Glass-transition temperature/Tg		℃	110	113	95	171	56
Shelf-life	-15 ~ -25℃	month(s)	1.5	2.5	1.5		—
	-40℃	month(s)	3.0				

